

WAFER CONNECTOR DIP WITH POST

3001 SERIES - 3.00MM



Specifications

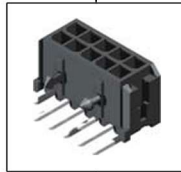
- Rated current: 5.0AMP
- Voltage rating: 250V AC/DC
- Contact resistance: 20mΩ max
- Withstand Voltage: 1500V AC/minute
- Insulation resistance: 1000MΩ min
- Operation temperature: -40°C to +105°C
- Contact material: Brass
- Contact plating: Tin Over Ni
- Solder Tabs material: Brass/Tin plated
- Insulator material: Polyester (UL94V-0)
- Standard: PA6T
- Max. processing Temp: 230°C for 30-60 seconds
260°C for 10 seconds

Ordering Information

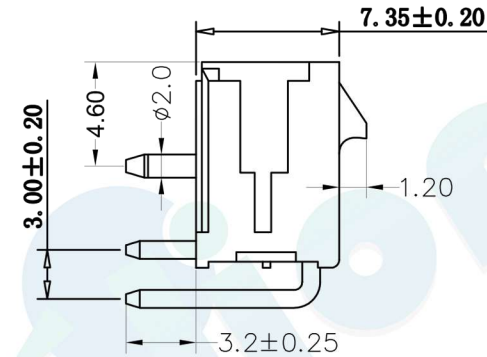
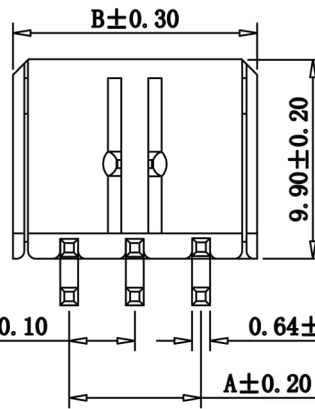
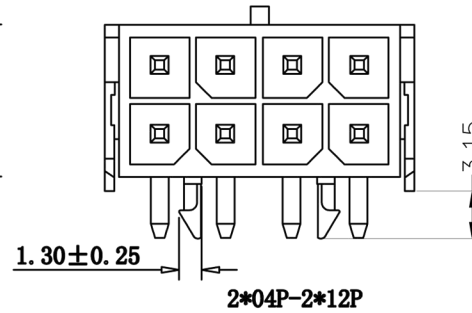
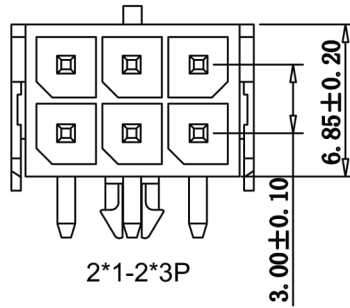
3001DR2 - (XX) X X (1)

1 2 3 4

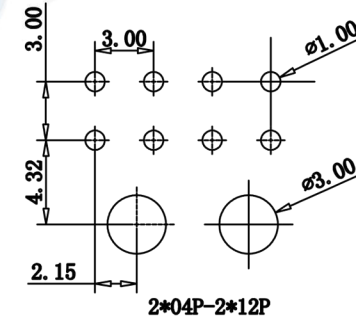
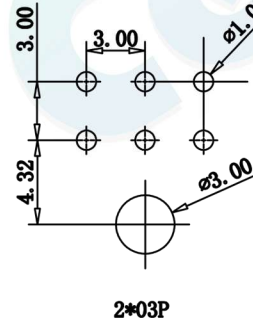
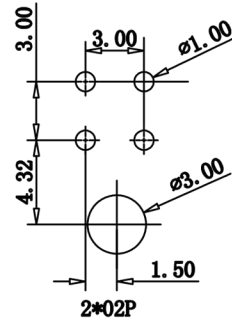
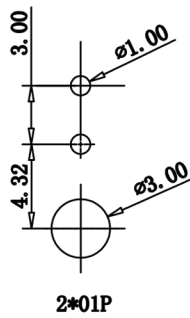
1. Connector Series
2. Number of pins per row (02→24)
3. Insulator Material Option
 - A = BK-PA6T
 - B = BK-PA9T
 - C = BK-LCP
4. Contact plating
 - A = Gold Flash
 - B = Gold Flash/Tin
 - C = Tin
 - D = Matte-Tin



(1). Packaging
 ∅=Pe Bag 1=Tube 2=Reel

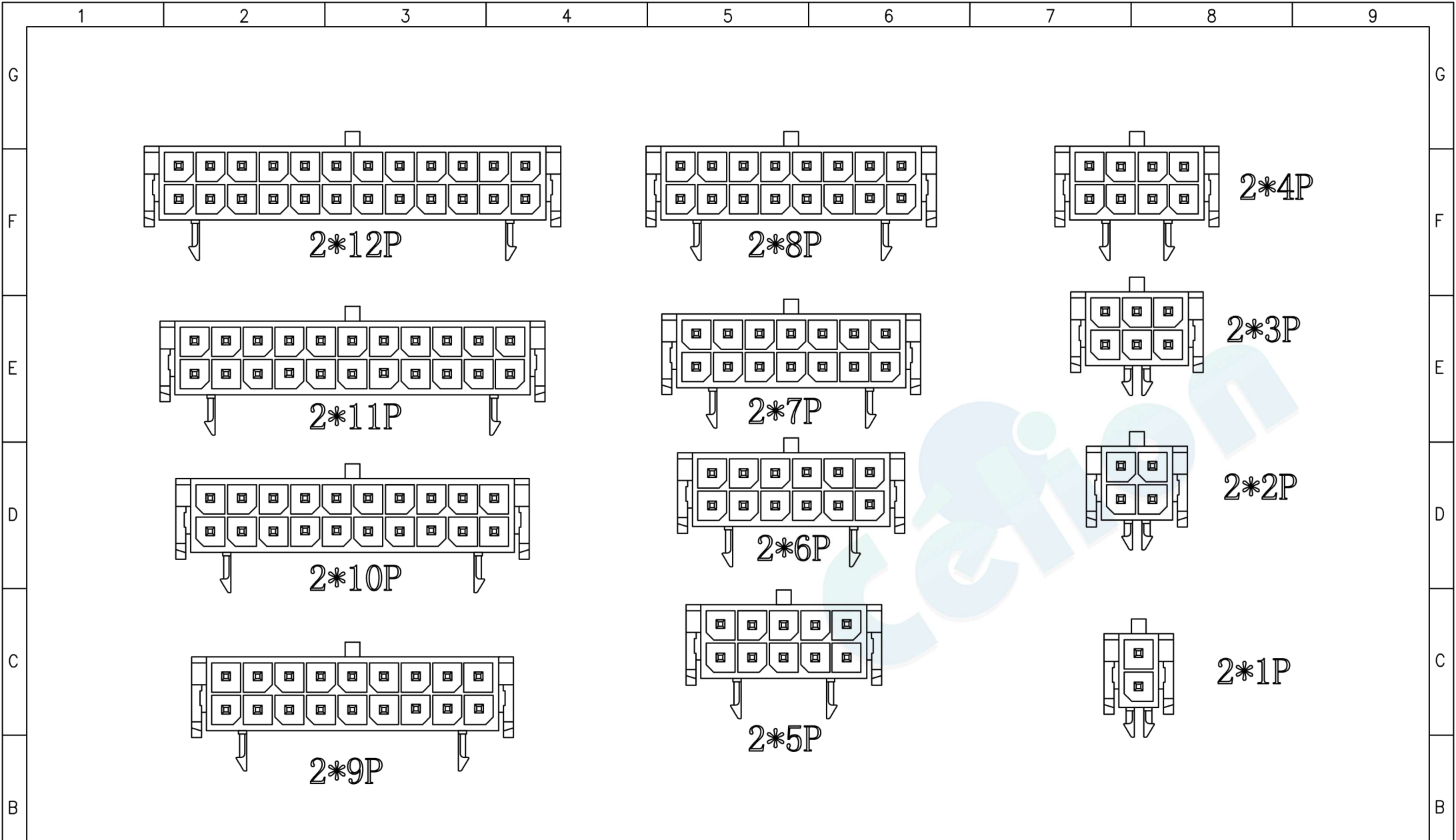



Circuit	Dimension	
	A	B
02	---	6.65
04	3.00	9.65
06	6.00	12.65
08	9.00	15.65
10	12.00	18.65
12	15.00	21.65
14	18.00	24.65
16	21.00	27.65
18	24.00	30.65
20	27.00	33.65
22	30.00	36.65
24	33.00	39.65



P. C. B. LAYOUT

				OPERATION		DRAW	BEN	12.04.18	SCALE	FIT	 votre partenaire en électronique	
				X.X	±0.30							
				X.XX	±0.20	APPROVE			SIZE	A4	PART NO.	3001DR2 - XXXX
				X.XXX	±0.10							
A0	2012.04.18	NEW DRAWING		Angle	±3°	PROJ.		TITLE:	MX3.00mm Wafer Npin 90° DIP			
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	DIM	TOL							



				OPERATION		DRAW	BEN	12.04.18	SCALE	FIT			
				X.X	±0.30				UNIT	mm			
				X.XX	±0.20	CHECK		SIZE	A4	PART NO.			3001DR2 - XXXX
				X.XXX	±0.10	APPROVE		SHEET	1/1	TITLE:			MX3.00mm Wafer Npin 90° DIP
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	Angle	±3°			PROJ.	